

fasteners 19 and the studs 22d and 22e can also be used to electrically connect the ground pattern of the main substrate 4 and the ground pattern of the sub-substrate 6 to the middle frame 22. Thus, the middle frame 22 functions as the ground member of the main substrate 4 and the sub-substrate 6 and therefore can cope with electromagnetic interference (EMI).

[0072] In the present embodiment, the main storage device 12 (second heating element) is mounted on the main substrate 4 and provided in a state of being thermally connected to the middle frame 22 through the heat conducting member 30. The heat conducting member 30 includes the grease 31 applied on the middle frame 22 and the sheet 32 interposed between the grease 31 and the main storage device 12.

[0073] With such a configuration, it is possible to transfer the heat from the main storage device 12 toward the middle frame 22 by thermal diffusion through the heat conducting member 30, thereby suppressing temperature increase of the main storage device 12 more effectively. Moreover, the sheet 32 interposed between the grease 31 and the main storage device 12 can prevent the grease 31 from coming into contact with and being electrically connected to a terminal of the main storage device 12, a terminal of the main substrate 4, and the like.

[0074] In the present embodiment, the storage holder 16 includes the bottom wall 16a (the heat insulating wall) at least covering the side surface 13a (second surface) of the auxiliary storage device 13 located in the opposite direction to the Y direction.

[0075] With such a configuration, the heat transferred from the middle frame 22, the main storage device 12, and the central processing unit 11 toward the auxiliary storage device 13 is suppressed by the bottom wall 16a, so that increase in temperature of the auxiliary storage device 13 can be suppressed.

[0076] Although embodiments of the present invention have been described above, the foregoing embodiments are illustrated by way of example and are not intended to limit the scope of the invention. The foregoing embodiments can be carried out in other various modes, and a variety of elimination, replacement, combination, and